

Form PTO-1449 (SNL-Modified) (2-91)
List of Patents and Publications
for Applicant's
Information Disclosure Statement
(use several sheets if necessary)

Atty Docket No: SD-7122/S-98,720
Serial Number:

APPLICANT: Kenneth A. Peterson, et al

GROUP: FILING DATE: 2/25/02

REFERENCE DESIGNATION

Ex'r Init		Document No.	Date	U.S. Patent Documents Name	Sub Class	Class	File Date
LT	AA	6,335,224	6/1/02	Protection of Microelectronic, ...	438/114		5/16/00
	AB	5,600,541	2/4/97	Vertical IC Chip Stack...	361/707		8/3/95
	AC	5,729,038	3/17/98	Silicon-Glass Bonded Wafers	257/460		12/15/95
	AD	5,357,056	10/18/94	Chip Carrier For Optical Device	174/524		3/23/93
	AE	5,864,381	1/26/99	Automated Pupil Remapping...	351/205		7/10/96
	AF	5,493,391	2/20/96	One Dimensional Wavefront...	356/121		7/11/94
	AG	5,352,852	10/4/94	Charge Coupled Device Package...	174/52.4		8/3/93
LT	AH	4,742,182	5/3/88	Flatpack for Hermetic...	174/52		11/6/86

11002 U.S. PTO
10/082961
02/25/02

		Document No.	Date	Foreign Patent Documents Name	Sub Class	Class	Translation Yes	No
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OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)

- LT |BA |Kenneth A. Peterson, et al; "Pre-Release Plastic Packaging of MEMS and IMEMS Devices"
Patent Application 09/572,720 filed 5/16/00.
- LT |BB |Kenneth A. Peterson, et al, "Microelectronic Device Package with an Integral Window";
Serial No. 09/571,335; filed 5/16/00; Notice of Allowance 2/6/01.
- LT |BC |M.L. Minges, et al., "Electronic Materials Handbook, Vol. 1, PACKAGING", ASM International, Materials
Park, OH, Jan., 1989, pp. 461-469.

Examiner:

Wong Thai

Date Considered: 2/5/03